



3.3V CMOS 18-BIT UNIVERSAL BUS DRIVER WITH 3-STATE OUTPUTS

IDT74ALVC16835

FEATURES:

- 0.5 MICRON CMOS Technology
- Typical $t_{sk(0)}$ (Output Skew) < 250ps
- ESD > 2000V per MIL-STD-883, Method 3015;
> 200V using machine model (C = 200pF, R = 0)
- 0.635mm pitch SSOP, 0.50mm pitch TSSOP,
and 0.40mm pitch TVSOP packages
- Extended commercial range of -40°C to $+85^{\circ}\text{C}$
- $V_{CC} = 3.3\text{V} \pm 0.3\text{V}$, Normal Range
- $V_{CC} = 2.7\text{V}$ to 3.6V , Extended Range
- $V_{CC} = 2.5\text{V} \pm 0.2\text{V}$
- CMOS power levels ($0.4\mu\text{W}$ typ. static)
- Rail-to-Rail output swing for increased noise margin

Drive Features for ALVC16835:

- High Output Drivers: $\pm 24\text{mA}$
- Suitable for heavy loads

DESCRIPTION:

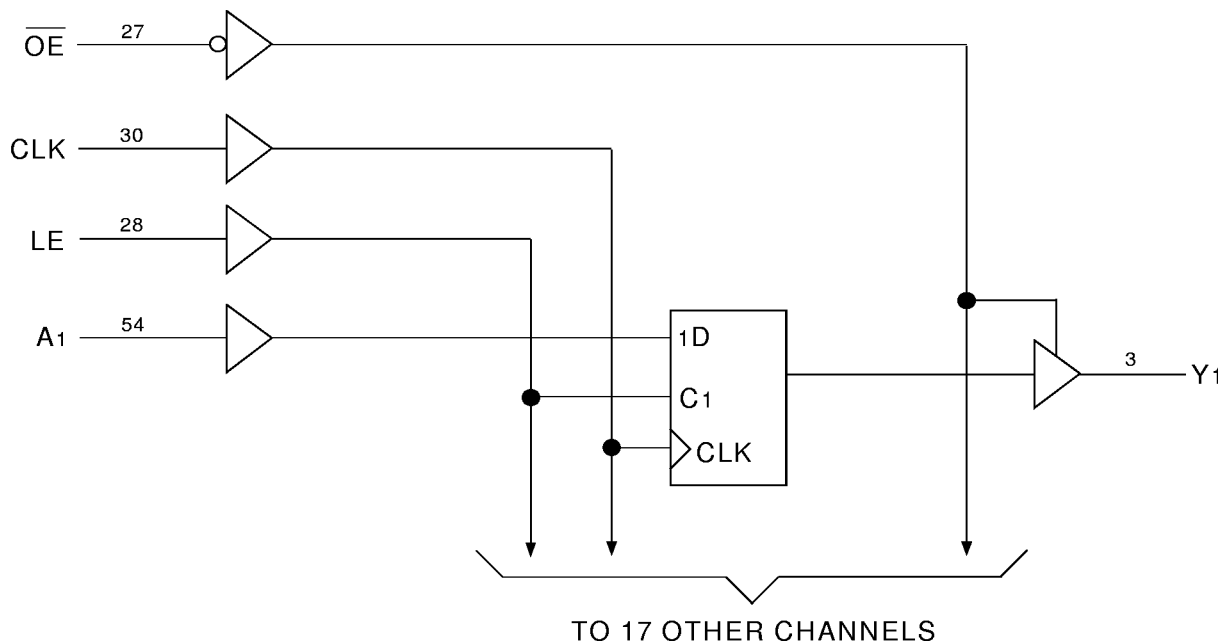
This 18-bit universal bus driver is built using advanced dual metal CMOS technology. Data flow from A to Y is controlled by the output-enable ($\overline{\text{OE}}$) input. The device operates in the transparent mode when the latch-enable (LE) input is high. The A data is latched if the clock (CLK) input is held at a high or low logic level. If LE is low, the A data is stored in the latch flip-flop on the low-to-high transition of CLK. When $\overline{\text{OE}}$ is high, the outputs are in the high-impedance state.

The ALVC16835 has been designed with a $\pm 24\text{mA}$ output driver. This driver is capable of driving a moderate to heavy load while maintaining speed performance.

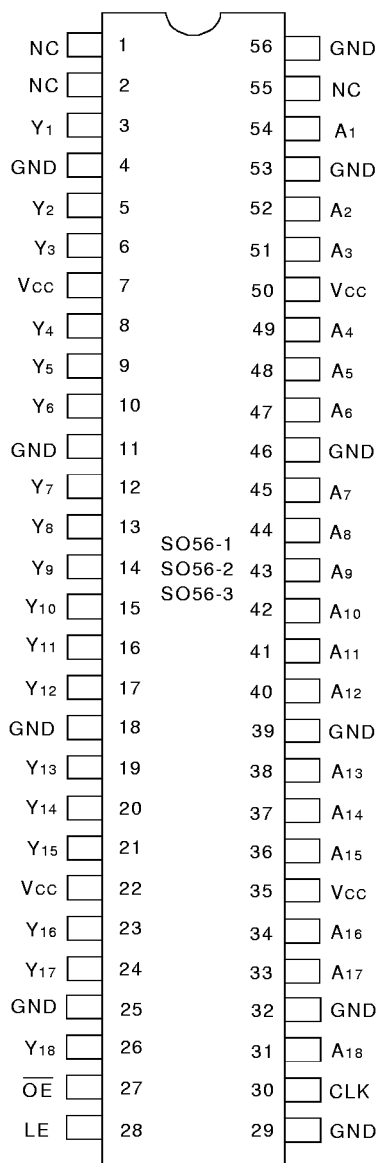
APPLICATIONS:

- SDRAM Modules
- PC Motherboards
- Workstations

Functional Block Diagram



PIN CONFIGURATION



SSOP/
TSSOP/ TVSOP
TOP VIEW

PIN DESCRIPTION

Pin Names	Description
$\overline{OE}$	3-State Output Enable Inputs (Active LOW)
CLK	Register Input Clock
LE	Latch Enable (Transparent HIGH)
Ax	Data Inputs
Yx	3-State Outputs
NC	No Internal Connection

ABSOLUTE MAXIMUM RATING (1)

Symbol	Description	Max.	Unit
$V_{TERM}^{(2)}$	Terminal Voltage with Respect to GND	- 0.5 to + 4.6	V
$V_{TERM}^{(3)}$	Terminal Voltage with Respect to GND	- 0.5 to $V_{CC} + 0.5$	V
TSTG	Storage Temperature	- 65 to + 150	°C
I _{OUT}	DC Output Current	- 50 to + 50	mA
I _{IK}	Continuous Clamp Current, $V_I < 0$ or $V_I > V_{CC}$	± 50	mA
I _{OK}	Continuous Clamp Current, $V_O < 0$	- 50	mA
I _{CC}	Continuous Current through each V _{CC} or GND	± 100	mA

NOTES:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- V_{CC} terminals.
- All terminals except V_{CC}.

CAPACITANCE (T_A = +25°C, f = 1.0MHz)

Symbol	Parameter ⁽¹⁾	Conditions	Typ.	Max.	Unit
C _{IN}	Input Capacitance	V _{IN} = 0V	5	7	pF
C _{OUT}	Output Capacitance	V _{OUT} = 0V	7	9	pF
C _{I/O}	I/O Port Capacitance	V _{IN} = 0V	7	9	pF

NOTE:

- As applicable to the device type.

FUNCTION TABLE⁽¹⁾

Inputs				Outputs
$\overline{OE}$	LE	CLK	Ax	Yx
H	X	X	X	Z
L	H	X	L	L
L	H	X	H	H
L	L	↑	L	L
L	L	↑	H	H
L	L	H	X	Y ₀ ⁽²⁾
L	L	L	X	Y ₀ ⁽³⁾

NOTES:

- H = HIGH Voltage Level
L = LOW Voltage Level
X = Don't Care
Z = High-Impedance
↑ = LOW-to-HIGH Transition
- Output level before indicated steady-state input conditions were established, provided that CLK is HIGH before LE went HIGH.
- Output level before the indicated steady-state input conditions were established.

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Operating Condition: TA = - 40°C to +85°C

Symbol	Parameter	Test Conditions		Min.	Typ. ⁽¹⁾	Max.	Unit
VIH	Input HIGH Voltage Level	VCC = 2.3V to 2.7V		1.7	—	—	V
		VCC = 2.7V to 3.6V		2	—	—	
VIL	Input LOW Voltage Level	VCC = 2.3V to 2.7V		—	—	0.7	V
		VCC = 2.7V to 3.6V		—	—	0.8	
IiH	Input HIGH Current	VCC = 3.6V	VI = VCC	—	—	± 5	μA
IiL	Input LOW Current	VCC = 3.6V	VI = GND	—	—	± 5	
IoZH	High Impedance Output Current (3-State Output pins)	VCC = 3.6V	VO = VCC	—	—	± 10	μA
IoZL			VO = GND	—	—	± 10	μA
VIK	Clamp Diode Voltage	VCC = 2.3V, IIN = - 18mA		—	- 0.7	- 1.2	V
VH	Input Hysteresis	VCC = 3.3V		—	100	—	mV
IcCL	Quiescent Power Supply Current	VCC = 3.6V		—	0.1	40	μA
IcCH		VIN = GND or VCC					
IcCZ							
ΔIcC	Quiescent Power Supply Current Variation	One input at VCC - 0.6V, other inputs at VCC or GND		—	—	750	μA

NEW16link

NOTE:

1. Typical values are at VCC = 3.3V, +25°C ambient.

OUTPUT DRIVE CHARACTERISTICS

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Max.	Unit
VOH	Output HIGH Voltage	VCC = 2.3V to 3.6V	IoH = - 0.1mA	VCC - 0.2	—	V
		VCC = 2.3V	IoH = - 6mA	2	—	
		VCC = 2.3V	IoH = - 12mA	1.7	—	
		VCC = 2.7V		2.2	—	
		VCC = 3.0V		2.4	—	
		VCC = 3.0V	IoH = - 24mA	2	—	
VOL	Output LOW Voltage	VCC = 2.3V to 3.6V	IoL = 0.1mA	—	0.2	V
		VCC = 2.3V	IoL = 6mA	—	0.4	
			IoL = 12mA	—	0.7	
		VCC = 2.7V	IoL = 12mA	—	0.4	
		VCC = 3.0V	IoL = 24mA	—	0.55	

NEW16link

NOTE:

1. VIH and VIL must be within the min. or max. range shown in the DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE table for the appropriate VCC range. TA = - 40°C to + 85°C.

OPERATING CHARACTERISTICS, $T_A = 25^\circ\text{C}$

Symbol	Parameter	Test Conditions	Vcc = 2.5V $\pm$ 0.2V	Vcc = 3.3V $\pm$ 0.3V	Unit
			Typical	Typical	
CPD	Power Dissipation Capacitance Outputs enabled	CL = 0pF, f = 10Mhz	26	31	pF
CPD	Power Dissipation Capacitance Outputs disabled		12	14	pF

SWITCHING CHARACTERISTICS⁽¹⁾

Symbol	Parameter	Vcc = 2.5V $\pm$ 0.2V		Vcc = 2.7V		Vcc = 3.3V $\pm$ 0.3V		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	
fMAX		150	—	150	—	150	—	MHz
tPLH tPHL	Propagation Delay Ax to Yx	1	4.2	—	4.2	1	3.6	ns
tPLH tPHL	Propagation Delay LE to Yx	1.3	5	—	4.9	1.3	4.2	ns
tPLH tPHL	Propagation Delay CLK to Yx	1.4	5.5	—	5.2	1.4	4.5	ns
tPZH tPZL	Output Enable Time $\overline{\text{OE}}$ to Yx	1.4	5.5	—	5.6	1.1	4.6	ns
tPHZ tPLZ	Output Disable Time $\overline{\text{OE}}$ to Yx	1	4.5	—	4.3	1.3	3.9	ns
tw	Pulse Duration, LE HIGH	3.3	—	3.3	—	3.3	—	ns
tw	Pulse Duration, CLK HIGH or LOW	3.3	—	3.3	—	3.3	—	ns
tsu	Setup Time, data before CLK $\uparrow$	2.2	—	2.1	—	1.7	—	ns
tsu	Setup Time, data before LE $\downarrow$, CLK HIGH	1.9	—	1.6	—	1.5	—	ns
tsu	Setup Time, data before LE $\downarrow$, CLK LOW	1.3	—	1.1	—	1	—	ns
th	Hold Time, data after CLK $\uparrow$	0.6	—	0.6	—	0.7	—	ns
th	Hold Time, data after LE $\downarrow$, CLK HIGH or LOW	1.4	—	1.7	—	1.4	—	ns
tsk(o)	Output Skew ⁽²⁾	—	—	—	—	—	500	ps

NOTES:

1. See test circuits and waveforms. $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$.
2. Skew between any two outputs of the same package and switching in the same direction.

SWITCHING CHARACTERISTICS FROM 0°C TO 65°C , $C_L=50$ pF

Symbol	Parameter	Vcc = 3.3V $\pm$ 0.15V		Unit
		Min.	Max.	
tPLH tPHL	Propagation Delay CLK to Yx	1.7	4.5	ns

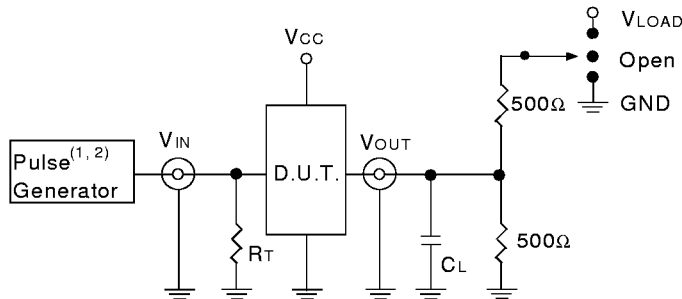
TEST CIRCUITS AND WAVEFORMS

TEST CONDITIONS

Symbol	V _{CC} (1)= 3.3V±0.3V	V _{CC} (1)= 2.7V	V _{CC} (2)= 2.5V±0.2V	Unit
V _{LOAD}	6	6	2 x V _{CC}	V
V _{IH}	2.7	2.7	V _{CC}	V
V _T	1.5	1.5	V _{CC} / 2	V
V _{LZ}	300	300	150	mV
V _{HZ}	300	300	150	mV
C _L	50	50	30	pF

NEWTEKlink

TEST CIRCUITS FOR ALL OUTPUTS



ALVC Link

DEFINITIONS:

C_L = Load capacitance; includes jig and probe capacitance.
R_T = Termination resistance; should be equal to Z_{OUT} of the Pulse Generator.

NOTES:

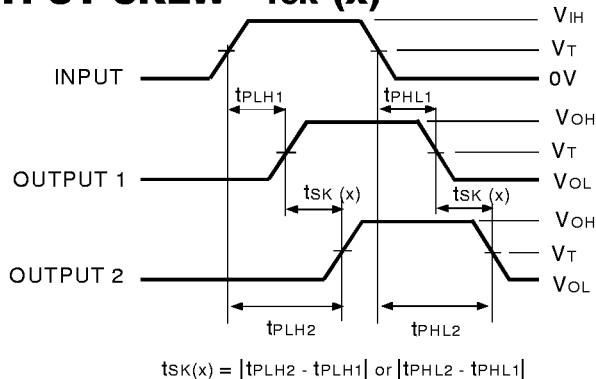
1. Pulse Generator for All Pulses: Rate ≤ 10MHz; t_F ≤ 2.5ns; t_R ≤ 2.5ns.
2. Pulse Generator for All Pulses: Rate ≤ 10MHz; t_F ≤ 2ns; t_R ≤ 2ns.

SWITCH POSITION

Test	Switch
Open Drain Disable Low Enable Low	V _{LOAD}
Disable High Enable High	GND
All Other tests	Open

NEWTEKlink

OUTPUT SKEW - t_{SK} (x)



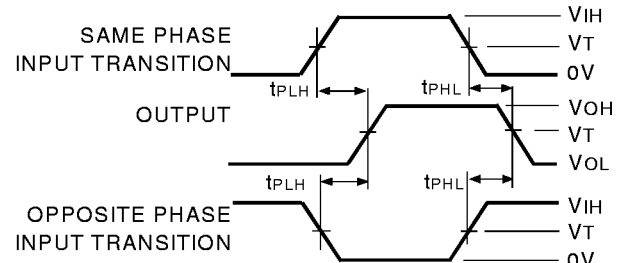
$$t_{SK}(x) = |t_{PLH2} - t_{PLH1}| \text{ or } |t_{PHL2} - t_{PHL1}|$$

ALVC Link

NOTES:

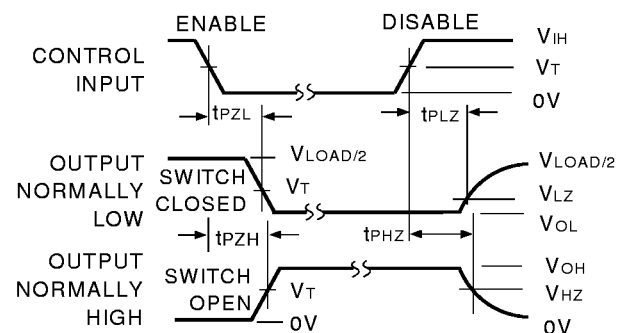
1. For t_{SK}(o) OUTPUT1 and OUTPUT2 are any two outputs.
2. For t_{SK}(b) OUTPUT1 and OUTPUT2 are in the same bank.

PROPAGATION DELAY



ALVC Link

ENABLE AND DISABLE TIMES

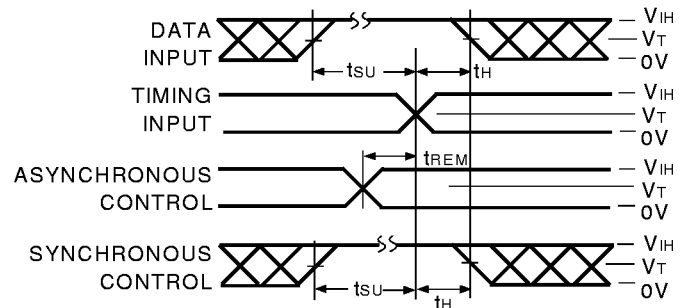


ALVC Link

NOTE:

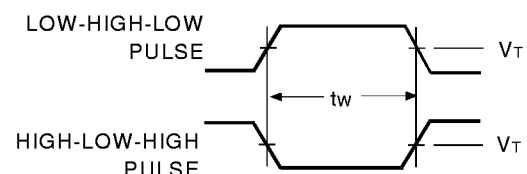
1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.

SET-UP, HOLD, AND RELEASE TIMES



ALVC Link

PULSE WIDTH



ALVC Link

ORDERING INFORMATION

IDT	XX	ALVC	X	XXX	XXX	XX	
	Temp. Range		Bus-Hold	Family	Device Type	Package	
						PV	Shrink Small Outline Package (SO56-1)
						PA	Thin Shrink Small Outline Package (SO56-2)
						PF	Thin Very Small Outline Package (SO56-3)
					835		18-Bit Universal Bus Driver with 3-State Outputs
				16			Double-Density with Resistors, $\pm 24\text{mA}$
			Blank				No Bus-Hold
					74		-40°C to $+85^{\circ}\text{C}$



CORPORATE HEADQUARTERS

2975 Stender Way
 Santa Clara, CA 95054

for SALES:

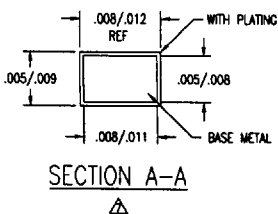
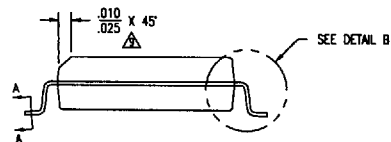
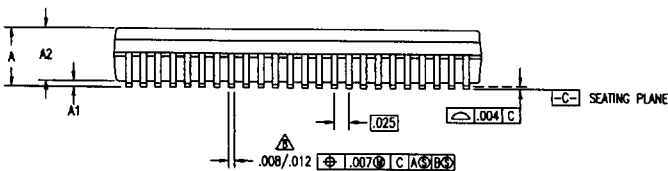
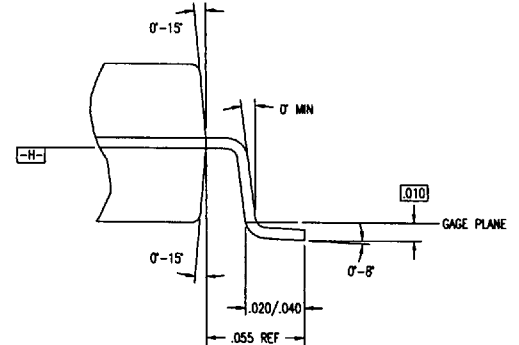
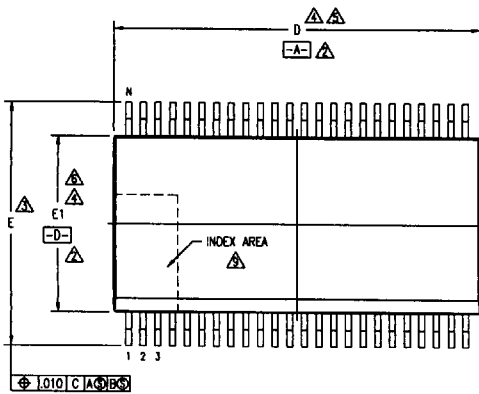
800-345-7015 or 408-727-6116
 fax: 408-492-8674
www.idt.com*

*To search for sales office near you, please click the sales button found on our home page or dial the 800# above and press 2.
 The IDT logo is a registered trademark of Integrated Device Technology, Inc.

PACKAGE DIAGRAM OUTLINES

SSOP

REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
17893	00	INITIAL RELEASE	07/15/90	A. FUNCELL
22377	01	REMOVE CHAMFER FROM PACKAGE	04/15/92	T. VU
27492	02	REDRAW TO JEDEC FORMAT	02/01/95	



TOLERANCES UNLESS SPECIFIED		Integrated Device Technology, Inc.	
DECIMAL	ANGULAR	2075 Slender Way, Santa Clara, CA 95054	
XXX	±	PHONE: (408) 727-8118	
XXX		FAX: (408) 482-8874	
XXX		TWC: 910-338-2070	
APPROVALS	DATE	TITLE	REV
DRAWN	08/15/90	PV PACKAGE OUTLINE	02
CHECKED		.300" BODY WIDTH SSOP	
		.025" PITCH	
		SIZE C	
		DRAWING No. PSC-4029	
		DO NOT SCALE DRAWING	

PACKAGE DIAGRAM OUTLINES SSOP (Continued)

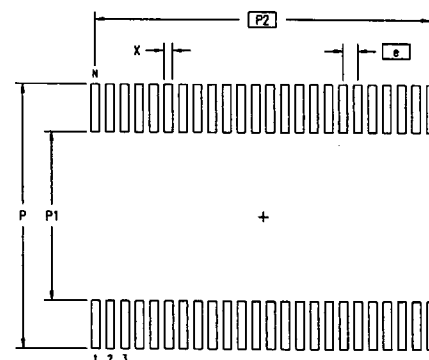
REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
17893	00	INITIAL RELEASE	07/15/90	A. FUNCELL
22377	01	REMOVE CHAMFER FROM PACKAGE	04/15/92	T. WJ
27492	02	REDRAW TO JEDEC FORMAT	02/01/95	

DWG #		S048-1				DWG #		S056-1			
SYMBOL	JEDEC VARIATION				NOTE	JEDEC VARIATION				NOTE	
	AA			AB							
	MIN	NOM	MAX	MIN		NOM	MAX				
A	.095	.102	.110		.095	.102	.110				
A1	.008	.012	.016		.008	.012	.016				
A2	.088	.090	.092		.088	.090	.092				
D	.620	.625	.630	4,5	.720	.725	.730	4,5			
E	.395	.405	.420	3	.395	.405	.420	3			
E1	.291	.295	.299	4,6	.291	.295	.299	4,6			
N	48				56						

NOTES:

- ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5M-1982
- DATUMS **-A-** AND **-B-** TO BE DETERMINED AT DATUM PLANE **-H-**
- DIMENSION E TO BE DETERMINED AT SEATING PLANE **-C-**
- DIMENSIONS D AND E1 ARE TO BE DETERMINED AT DATUM PLANE **-H-**
- DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS AND GATE BURRS SHALL NOT EXCEED .006 PER SIDE
- DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSIONS. INTERLEAD FLASH OR PROTRUSIONS SHALL NOT EXCEED .015 PER SIDE
- THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .005 AND .010 FROM LEAD TIP
- LEAD WIDTH DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION IS .004 IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT
- THE CHAMFER ON THE PACKAGE BODY IS OPTIONAL. IF IT IS NOT PRESENT, A VISUAL INDEX FEATURE MUST BE LOCATED WITHIN THE ZONE INDICATED
- ALL DIMENSIONS ARE IN INCHES
- THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MO-118, VARIATION AA & AB

LAND PATTERN DIMENSIONS



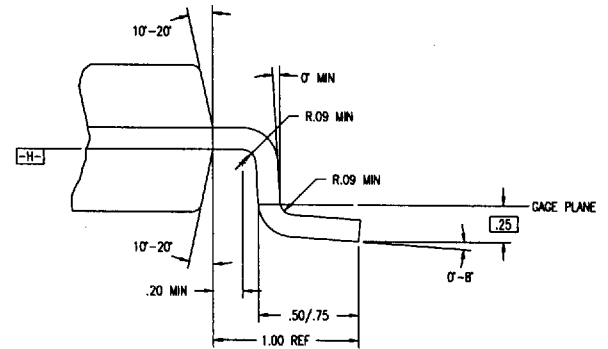
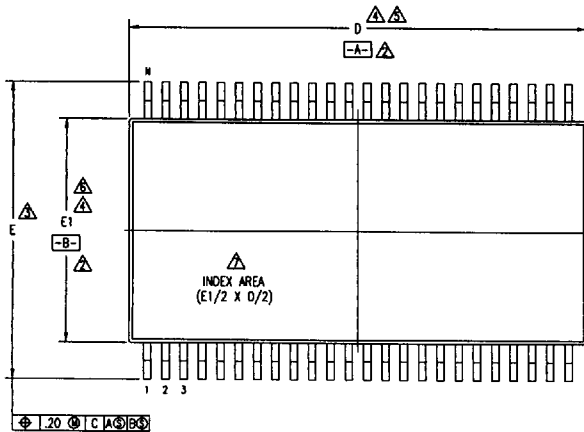
	MIN	MAX	MIN	MAX
P	.450	.458	.450	.458
P1	.282	.290	.282	.290
P2	.575 BSC		.675 BSC	
X	.010	.018	.010	.018
e	.025 BSC		.025 BSC	
N	48		56	

TOLERANCES UNLESS SPECIFIED		Integrated Device Technology, Inc.	
DECIMAL	ANGULAR	2075 Stoner Way, Santa Clara, CA 95054	
X.XX	±	PHONE: (408) 727-8116	
X.XXX	±	FAX: (408) 482-8874	
X.XXX	±	TW: 810-338-2070	
APPROVALS	DATE	TITLE	REV
DRN	06/15/90	PV PACKAGE OUTLINE	
CHECKED		.300" BODY WIDTH SSOP	
		.025" PITCH	
		SIZE	REV
		C	02
		DRAWING No.	
		PSC-4029	
		DO NOT SCALE DRAWING	

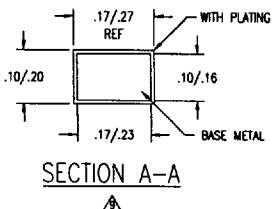
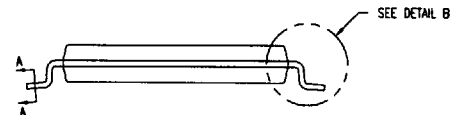
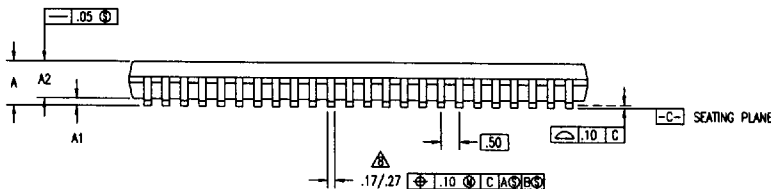
PACKAGE DIAGRAM OUTLINES

TSSOP

REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
23757	00	INITIAL RELEASE	02/15/93	T. VU
26315	01	CHANGE DIMS A1 & A2	05/18/94	DG
26490	02	CHANGE DIM A1	07/21/94	T. VU
27494	03	REDRAW TO JEDEC FORMAT	03/08/95	



DETAIL B



SECTION A-A

TOLERANCES UNLESS SPECIFIED		Integrated Device Technology, Inc.	
DECIMAL	ANGULAR	2975 Slender Way, Santa Clara, CA 95054	
XXX.X	±	PHONE: (408) 727-8118	
XXXX.X		FAX: (408) 492-8674	
XXXX.X		TW: 910-336-2070	
APPROVALS	DATE	TITLE	REV
DRAWN	01/15/93	PA PACKAGE OUTLINE	
CHECKED		6.10 mm BODY WIDTH TSSOP	
		.50 mm PITCH	
		SIZE	DRAWING No.
		C	PSC-4039
			03
			DO NOT SCALE DRAWING

PACKAGE DIAGRAM OUTLINES TSSOP (Continued)

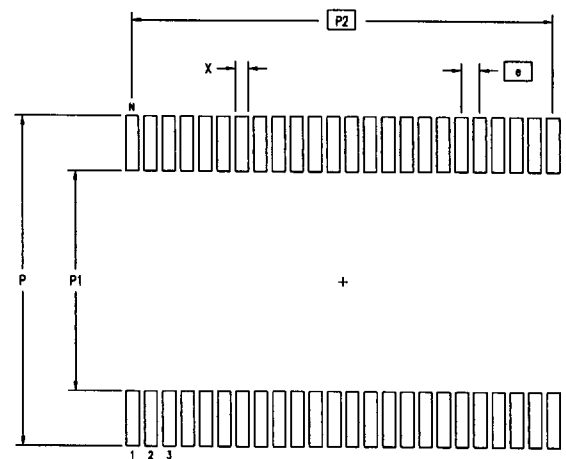
DWG #		S048-2			DWG #		S056-2				
SYMBOL	JEDEC VARIATION				NOTE	JEDEC VARIATION				NOTE	
	ED					EE					
	MIN	NOM	MAX			MIN	NOM	MAX			
A	—	—	1.10			—	—	1.10			
A1	.05	—	.15			.05	—	.15			
A2	.85	1.00	1.05			.85	1.00	1.05			
D	12.40	12.50	12.60	4,5		13.90	14.00	14.10	4,5		
E	7.95	8.10	8.25	3		7.95	8.10	8.25	3		
E1	6.00	6.10	6.20	4,6		6.00	6.10	6.20	4,6		
N	48					56					

NOTES:

- ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5M-1982
- DATUMS $\square$ -A- and $\square$ -B- TO BE DETERMINED AT DATUM PLANE $\square$ -H-
- DIMENSION E TO BE DETERMINED AT SEATING PLANE $\square$ -C-
- DIMENSIONS D AND E1 ARE TO BE DETERMINED AT DATUM PLANE $\square$ -H-
- DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED .15 mm PER SIDE
- DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSIONS. INTERLEAD FLASH OR PROTRUSIONS SHALL NOT EXCEED .25 mm PER SIDE
- DETAIL OF PIN 1 IDENTIFIER IS OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED
- LEAD WIDTH DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION IS .08 mm IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT
- THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .10 AND .25 mm FROM THE LEAD TIP
- ALL DIMENSIONS ARE IN MILLIMETERS
- THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MQ-153, VARIATION ED & EE

REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
23757	00	INITIAL RELEASE	02/15/93	T. VU
26315	01	CHANGE DIMS A1 & A2	05/18/94	DG
26490	02	CHANGE DIM A1	07/21/94	T. VU
27494	03	REDRAW TO JEDEC FORMAT	03/08/95	

LAND PATTERN DIMENSIONS



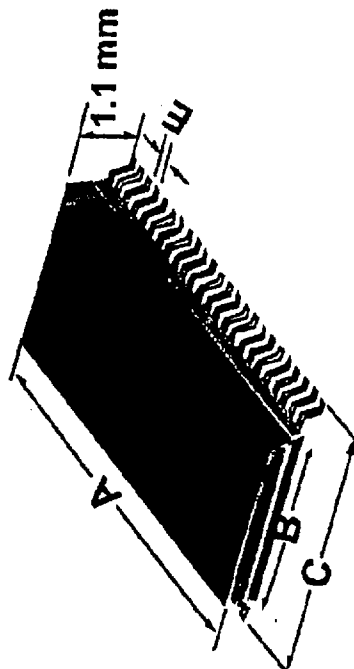
	MIN	MAX	MIN	MAX
P	8.90	9.10	8.90	9.10
P1	5.90	6.10	5.90	6.10
P2	11.50	BSC	13.50	BSC
X	.30	.40	.30	.40
e	.50	BSC	.50	BSC
N	48		56	

TOLERANCES UNLESS SPECIFIED		Integrated Device Technology, Inc.	
DECIMAL	ANGULAR	2975 Slender Way, Santa Clara, CA 95054	
XXX.X	±	PHONE: (408) 727-8118	
XXXX.XX		FAX: (408) 482-8874	
XXXX.XXX		TWC: 910-338-2070	
APPROVALS	DATE	TITLE	PA PACKAGE OUTLINE
DRAWN	01/19/93	6.10 mm BODY WIDTH TSSOP	
CHECKED		.50 mm PITCH	
		SIZE	C
		DRAWING No.	PSC-4039
		REV	03
		DO NOT SCALE DRAWING	



TVSOP

The Most Compact Double Density Package

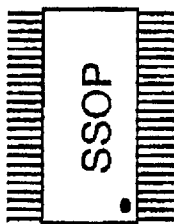


TVSOP Package	Typical Dimensions (in mm)				Area (mm ²)
	A	B	C	E	
48 Pin	9.80	4.40	6.40	0.40	63.00
56 Pin	11.30	4.40	6.40	0.40	72.30
80 Pin	17.00	6.10	8.10	0.40	137.80
100 Pin	20.80	6.10	8.10	0.40	168.50



Double Density Packaging

48-Pin



16.0 x 10.3 x 2.6 mm
pin pitch = 0.635 mm
Area = 164.8 mm²

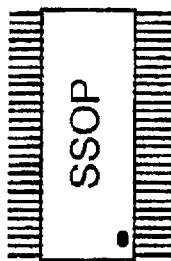


12.5 x 8.1 x 1.1 mm
pin-pitch = 0.5 mm
Area = 101.3 mm²



9.8 x 6.4 x 1.1 mm
pin-pitch = 0.4 mm
Area = 62.7 mm²

56-Pin



18.4 x 10.3 x 2.6 mm
pin-pitch = 0.635 mm
Area = 189.5 mm²



14.0 x 8.1 x 1.1 mm
pin-pitch = 0.5 mm
Area = 113.4 mm²



11.3 x 6.4 x 1.1 mm
pin-pitch = 0.4 mm
Area = 72.3 mm²

TVSOP	Area (mm ²)	%Smaller Than SSOP	%Smaller Than TSSOP
48 pin	63.00	61.9	38.0
56 pin	72.30	62.2	36.0